

DOCKET: CU-2417

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Takahiro IJIMA et al. /

Serial No.: 09/736,864 /

Filed: December 14, 2000 /

For: INTERCONNECTION SUBSTRATE
HAVING METAL COLUMNS COVERED BY A
RESIN FILM AND MANUFACTURING
METHOD THEREOF

GRP ART UNIT : 2815

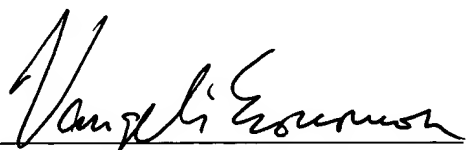
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Certification under 37 C.F.R. §1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on July 17, 2003.


Vangelis Economou, Reg. No. 32,341

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated May 22, 2003, please amend the above-captioned application as follows:

IN THE CLAIMS:

Please substitute the following Claims 1 and 11 in the revised format for the pending Claim 1 and 11.